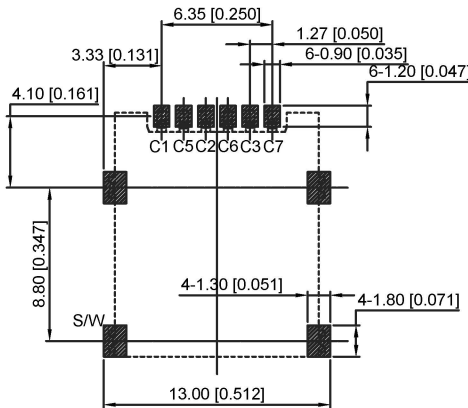
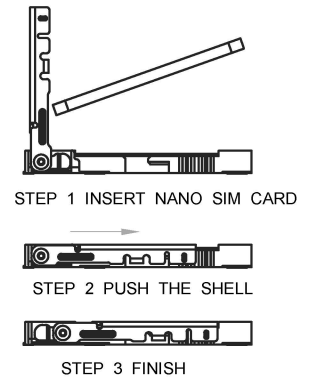
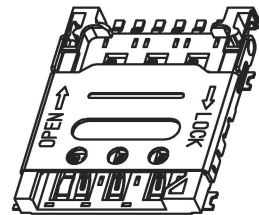
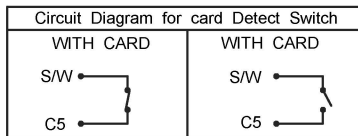


| PIN NO. | PIN NAME |
|---------|------------|
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |
| S/W | Switch Pin |



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05

■ SMT SOLDER AREA



- NOTES:
- MATERIAL:
 - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
 - Terminal: Copper Alloy, T=0.12mm.
 - Shell: SUS, T=0.20mm.
 - FINISH:
 - Terminal: Plated Gold on the Contact Area and Solder Tails
 - Peg: Plated Gold on the Solder Tails.
 - SPECIALITY:
 - Rated current: 0.5A
 - Rated voltage: 50V
 - Contact Resistance: 50mΩ MAX
 - Insulation Resistance: 100MΩMIN 100V DC
 - Dielectric withstanding voltage: 100V AC.
 - Durability Cycles: 5000 Cycles.
 - Solder ability: 245±5°C, 5±0.5s.
 - Operating condition: Temperature: -30°C~+80°C Humidity: 80% R.H MAX

| ITEM | PART NAME | QTY | MATERIAL | FINISHING |
|------|-----------|-----|--------------------------|-----------|
| ③ | Shell | 1 | SUS | |
| ② | Terminal | 6 | COPPER ALLOY | |
| ① | Housing | 1 | HI-TEMP. PLASIC UL 94V-0 | BLACK |

广东星坤科技股份有限公司

生效日期

文件工程章

REVISIONS
www.helloxkb.com www.helloxkb.com

| DSND | DATE | SCALE: N/A | MODEL TYPE: |
|---------------------------------------|------|-------------|-----------------------|
| DWN | DATE | VIEW: | SIM CARD CONN |
| CHKD | DATE | UNIT: mm/in | PART NO.: |
| APPD | DATE | SIZE: A4 | DWG NO.: |
| | | | XKNANO-1306 |
| XKB INDUSTRIAL PRECISION CO., LIMITED | | | WEIGHT SHEET REVISION |
| | | | 1.0g 1/1 A0 |